

Amendment to Specification

Please amend the paragraphs numbered below as shown:

[0085] The advantage of the contact pad 350 as in Figs. 16A, 16B is that the solder 930 does not wet the dielectric 110.2 on the bottom of opening 210B. Therefore, more solder will gather closer to contact 340, and the solder will reach higher up along the contact surface. This is believed to improve the mechanical strength and electrical conductivity of the solder joint. Less solder is needed for good mechanical strength and electrical conductivity, so the diameter of opening 230B 210B can be reduced (this diameter controls the solder volume by controlling the volume of the solder paste in opening 230B 210B).

[0087] In Fig. 17, contact pad 350 includes two conductive layers 910.1, 910.2. The bottom layer 910.1 covers the whole bottom of opening 230B 210B, and the top layer 910.2 covers only a portion of the bottom of opening 230B 210B. Bottom layer 910.1 is less solder wettable than the top layer 910.2. In still other embodiments, bottom layer 910.1 does not cover the whole bottom of opening 230B 210B, and the top layer 910.2 covers a smaller portion of the bottom of opening 230B 210B than the top layer 910.1.